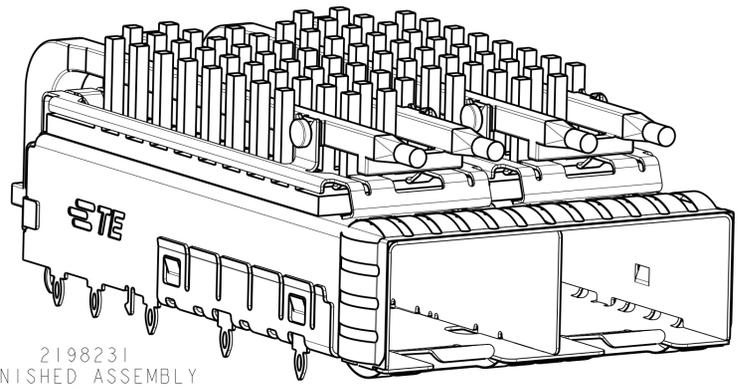


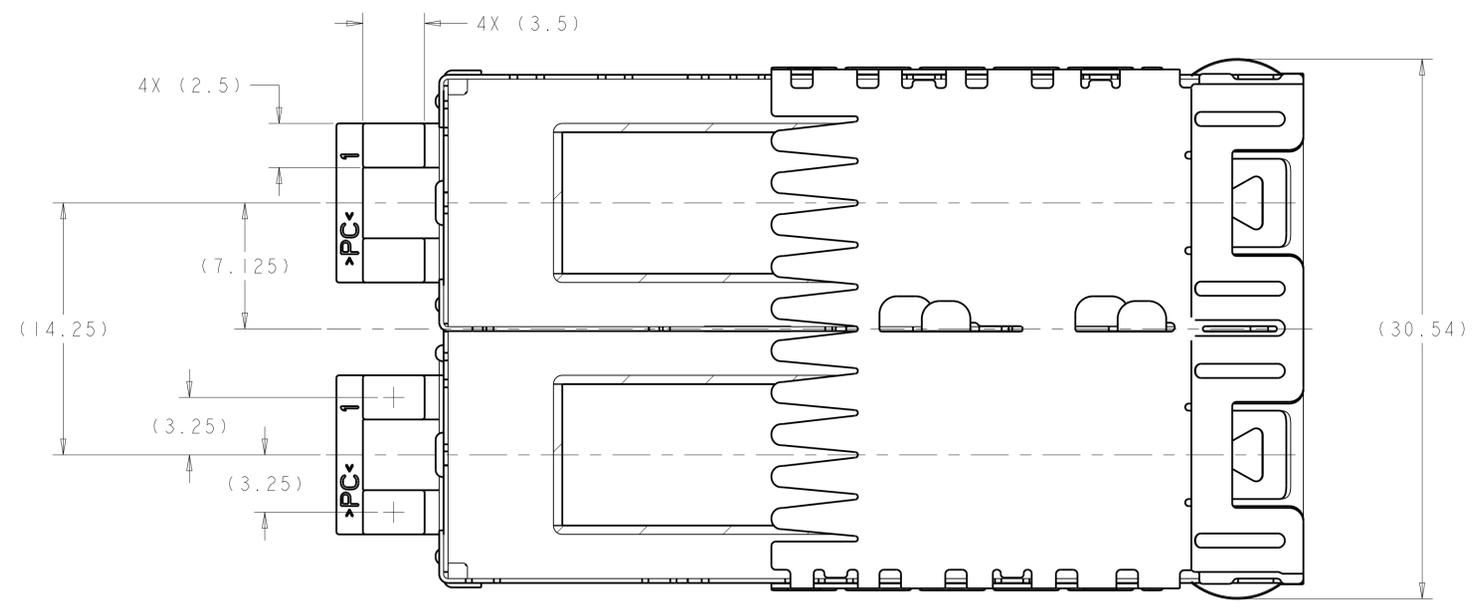
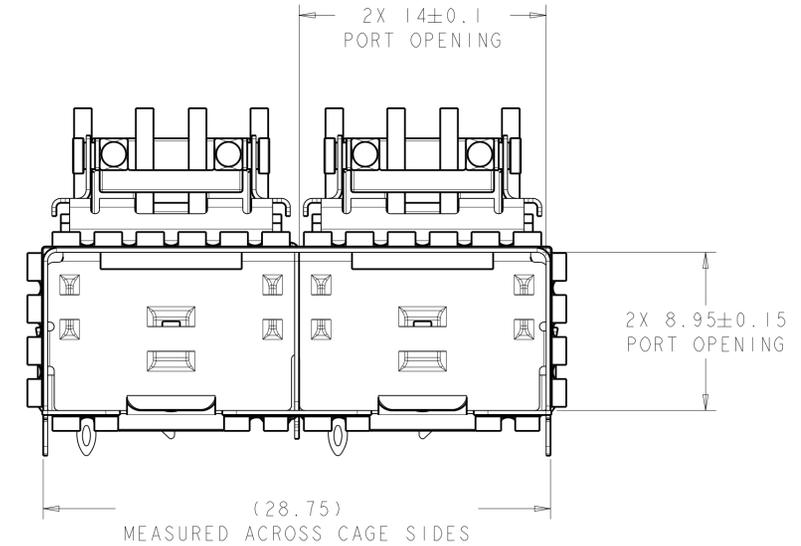
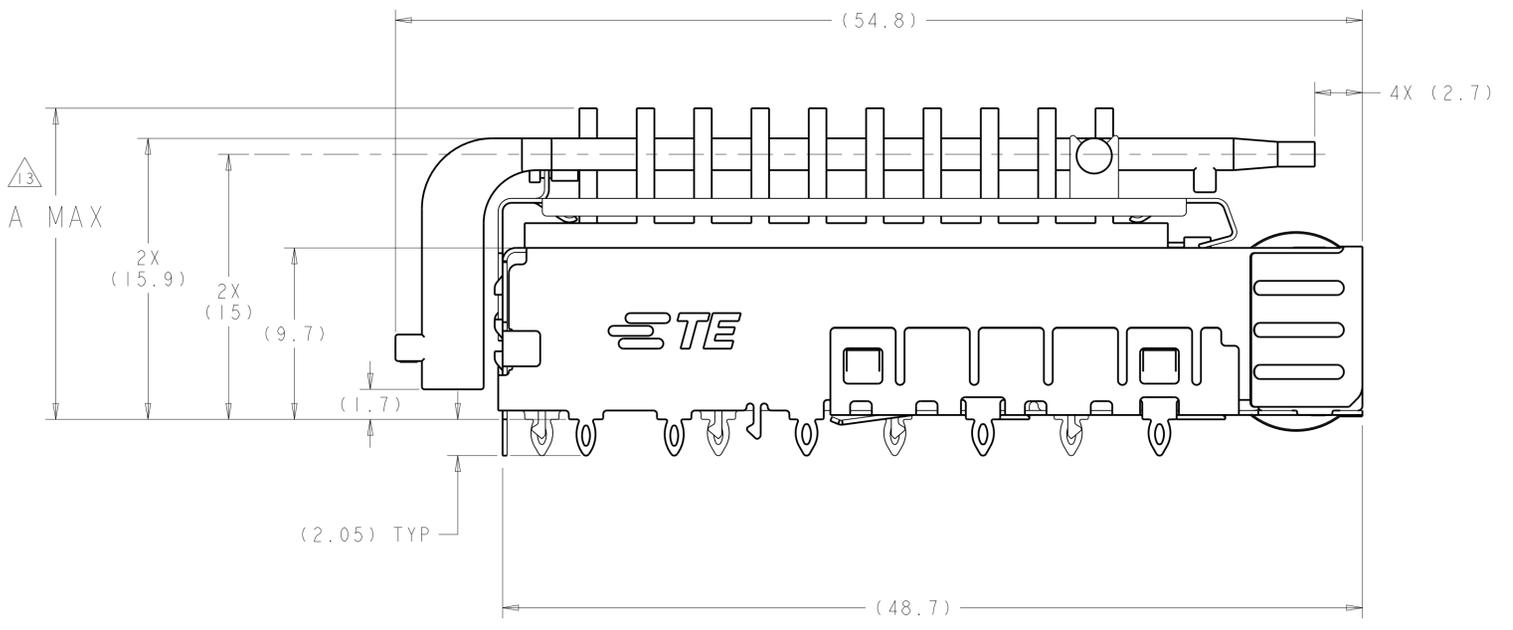
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GP	00	REV	DATE	BY	CHK
		A	RELEASED PER ECO-12-013192	18OCT2012	BMM MRS
		A1	RELEASED PER ECO-14-008488	06JUNE2014	PP SH



2198231
FINISHED ASSEMBLY
SCALE 4:1

- 1. MATERIAL:
CAGE ASSEMBLY: 0.25mm THICK NICKEL SILVER ALLOY
EMI SPRINGS: COPPER ALLOY
HEAT SINK: ALUMINUM
HEAT SINK/LIGHTPIPE CLIP: STAINLESS STEEL.
LIGHTPIPE: POLYCARBONATE, CLEAR
- 2. FINISH:
SPRINGS: MINIMUM OF 0.8um TIN PLATE OVER MINIMUM OF 0.8um NICKEL UNDERPLATE. NON-PLATED EDGES PERMISSIBLE.
HEAT SINK: ELECTROLESS NICKEL
HEAT SINK CLIP: PASSIVATE.
- 3. DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.
- 4. PADS AND VIAS CHASSIS GROUND.
- 5. MATES WITH SFP MSA COMPLIANT RECEIVERS.
- 6. INTERPRETATION OF DATUM REFERENCE FRAME IN ACCORDANCE WITH SECT 4.4.1.1 OR ASME Y14.5M-1994.
- 7. MINIMUM PC BOARD THICKNESS:
SINGLE SIDED: 1.5mm
DOUBLE SIDED: 2.25mm
- 8. HOLE PATTERN REPEATS FOR EACH PORT, SPACING BETWEEN PORTS IS 14.25mm.
- 9. REFERENCE APPLICATION SPEC. 114-13120, HOLE A, FOR RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.

- 10. REFERENCE APPLICATION SPEC. 114-13120, HOLE B, FOR RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.
- 11. CERTAIN MATING TRANCEIVERS MAY REQUIRE ADDITIONAL PCB THICKNESS THAT WOULD NEED TO BE DETERMINED BY THE CUSTOMER.
- 12. PRODUCT COMPLIES WITH SPECIFICATION SFF-8433 IMPROVED PLUGGABLE FORM FACTOR FOR SFP+ GANGED CAGES.
- 13. DIMENSION APPLIES PRIOR TO INSERTION OF SFP MODULE.
- 14. HEATSINK, HEATSINK CLIP, AND LIGHTPIPE SHIPPED UNASSEMBLED TO CAGE ASSEMBLY. CAGE ASSEMBLY TO BE PRESSED INTO PCB PRIOR TO ATTACHING HEATSINK, HEATSINK CLIP, AND LIGHTPIPE TO THE CAGE ASSEMBLY.
- 15. PACKAGED AS A COMPLETE ASSEMBLY.

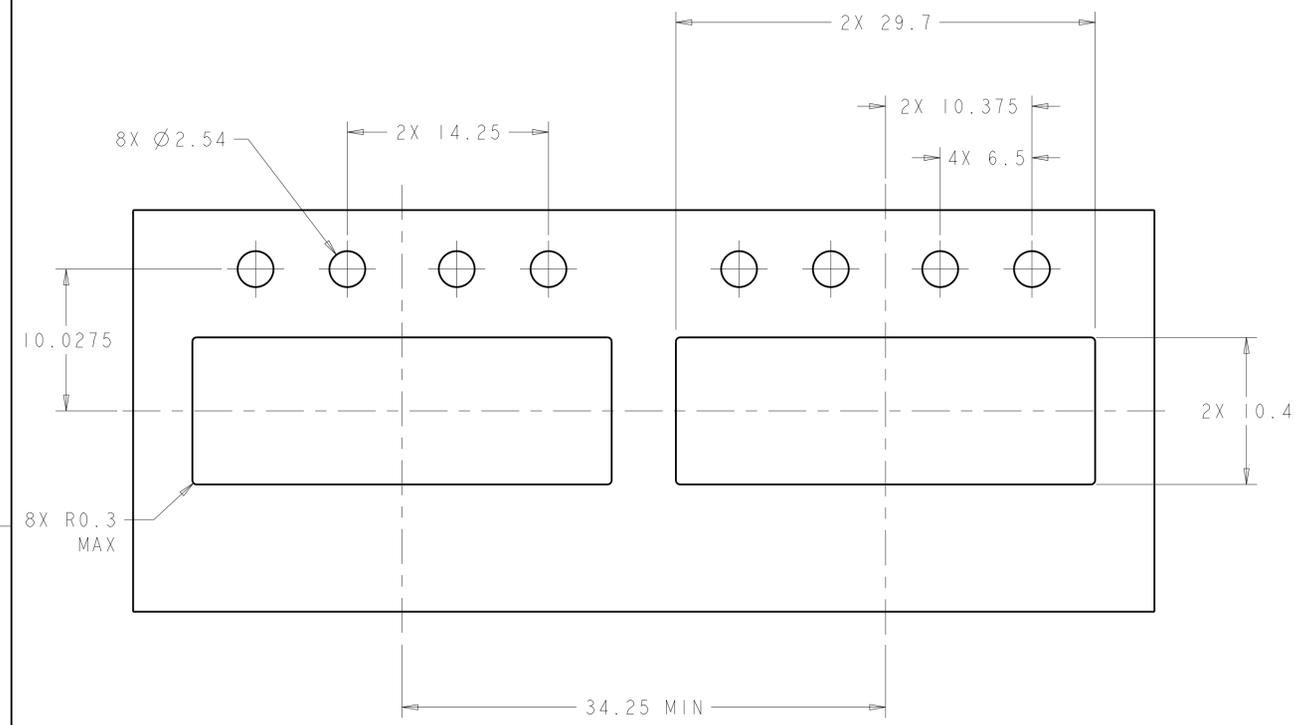


22.5	NETWORKING, TALL	2198231-4
18.1	NETWORKING, SHORT	2198231-3
15.5	SAN	2198231-2
13.2	PCI	2198231-1
A MAX	DESCRIPTION	PART NUMBER

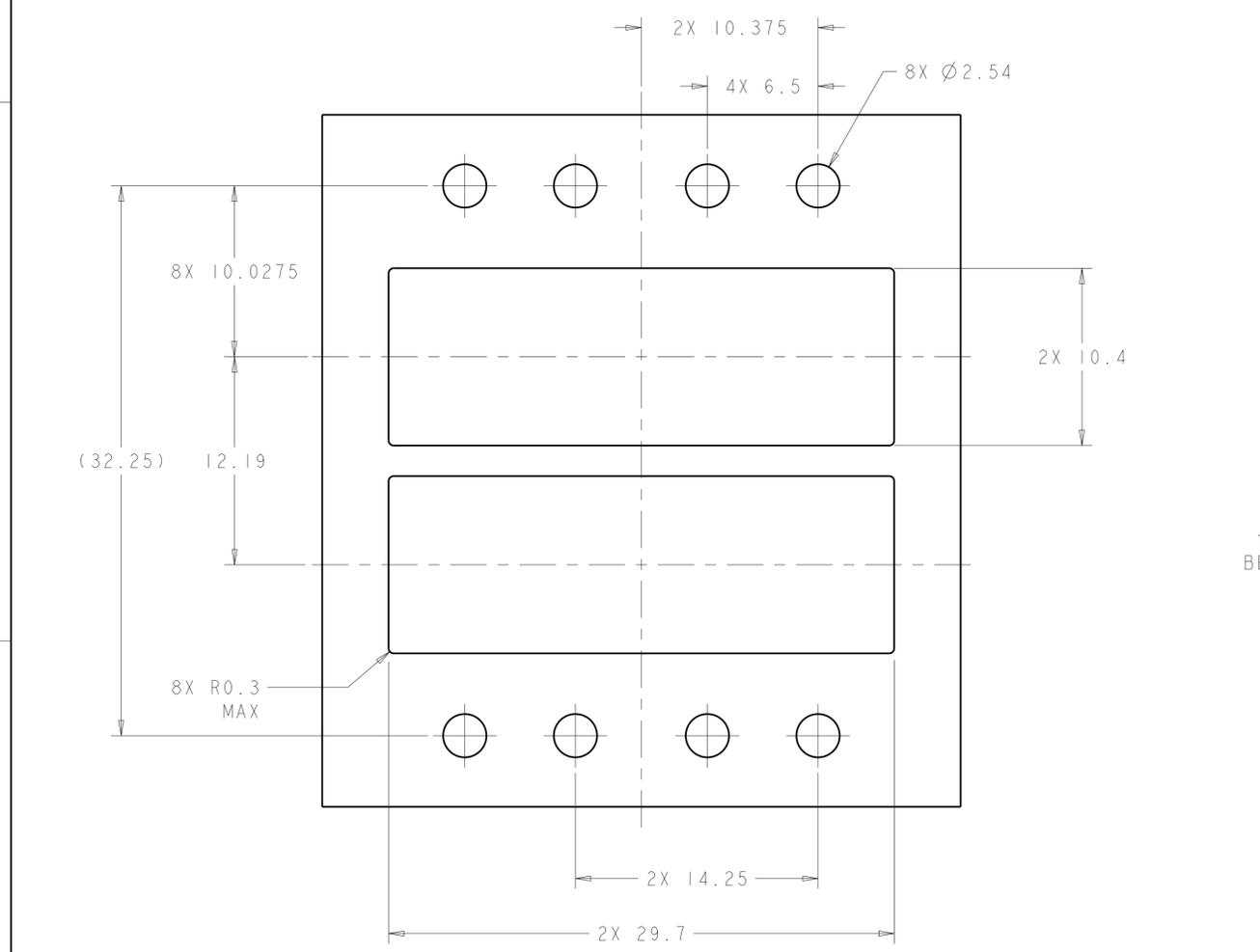
THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN: B. MATTHEWS 15NOV2011	TE Connectivity
DIMENSIONS: mm		CHK: M. SCHMITT 15NOV2011	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD: M. SCHMITT 15NOV2011	NAME: SFP+ ENHANCED 1X2 CAGE ASSEMBLY, PRESS-FIT, EXTERNAL EMI SPRINGS WITH HEATSINK AND LIGHTPIPE PRODUCT SPEC: 108-2364 APPLICATION SPEC: 114-13120 SIZE: CAGE CODE DRAWING NO WEIGHT: - CUSTOMER DRAWING
0 PLC ±0.13		RESTRICTED TO	
1 PLC ±0.1		SCALE: 5:1	
2 PLC ±0.08		SHEET 1 OF 4	
3 PLC ±0.05		REV: A1	
4 PLC ±0.05			
ANGLES			

LOC	DIST	REV	DATE	BY	APPV
GP	00				

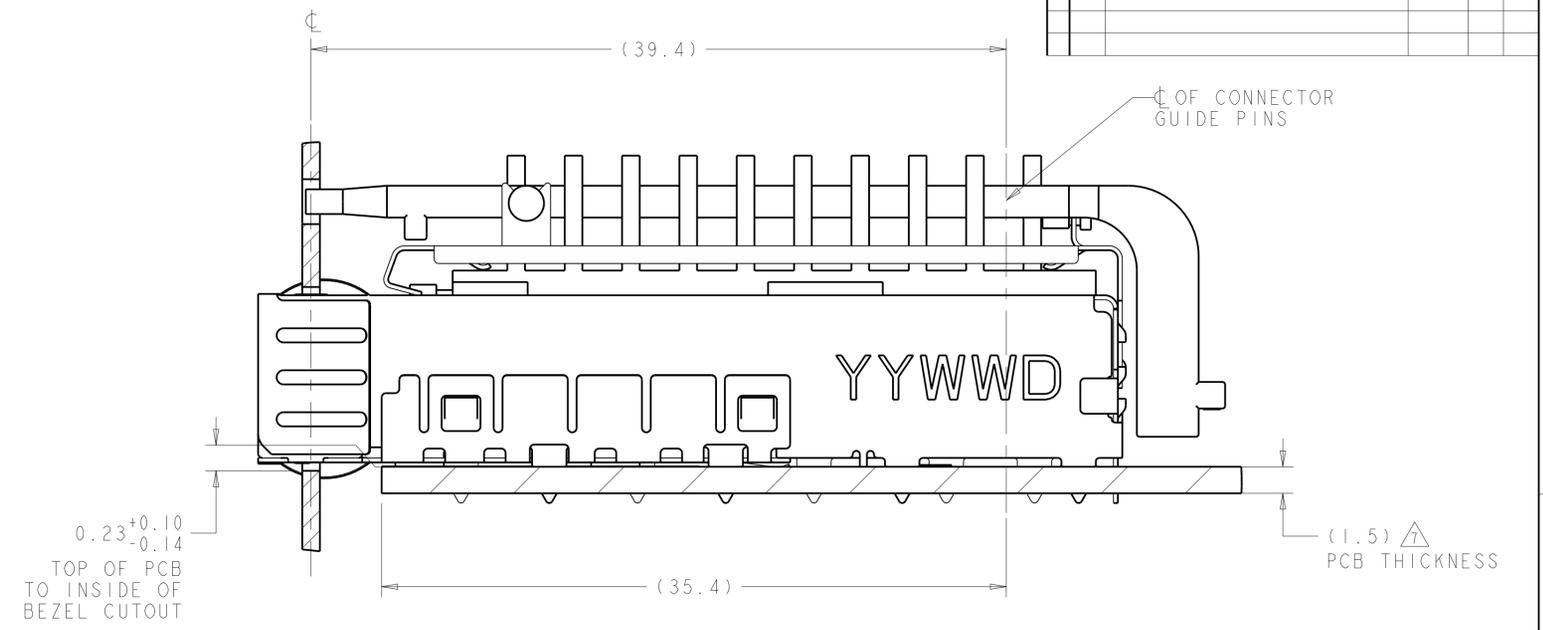
REVISIONS			
NO.	DESCRIPTION	DATE	BY
1	SEE SHEET 1		



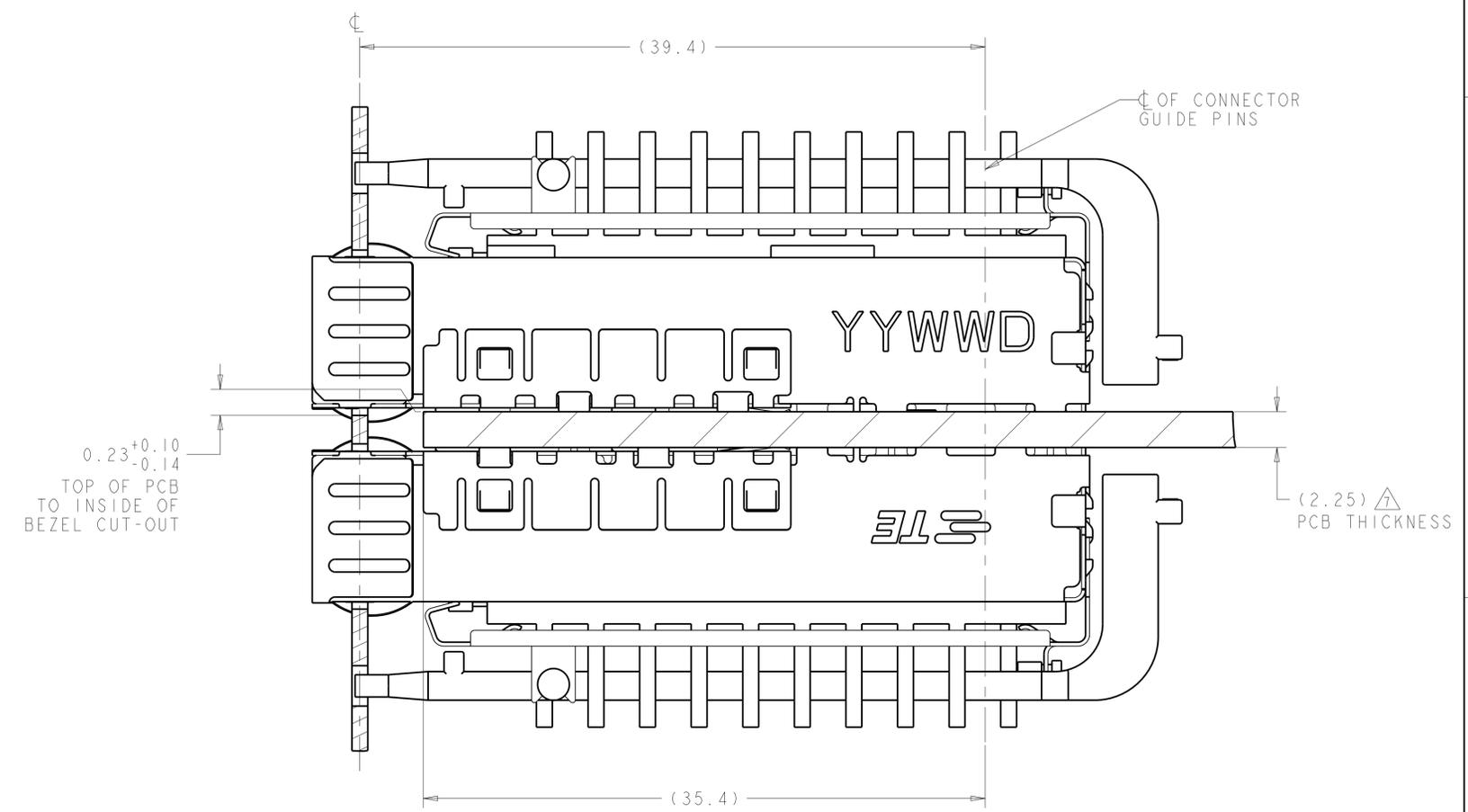
RECOMMENDED BEZEL CUT-OUT
SINGLE SIDED APPLICATIONS
SCALE 4:1



RECOMMENDED BEZEL CUT-OUT
BELLY TO BELLY APPLICATIONS



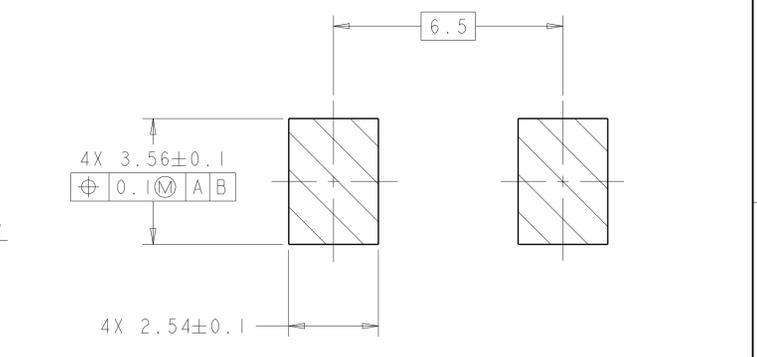
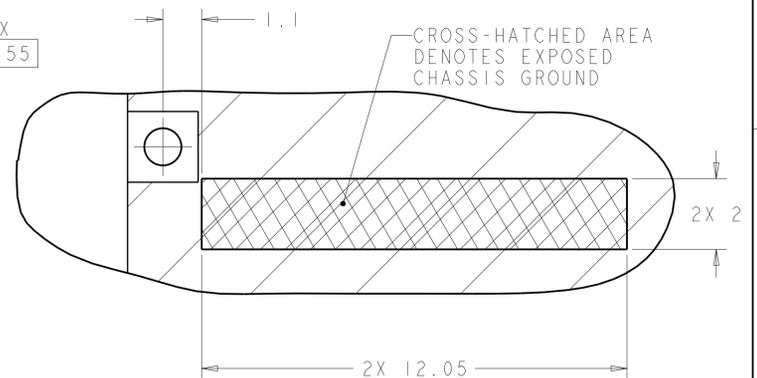
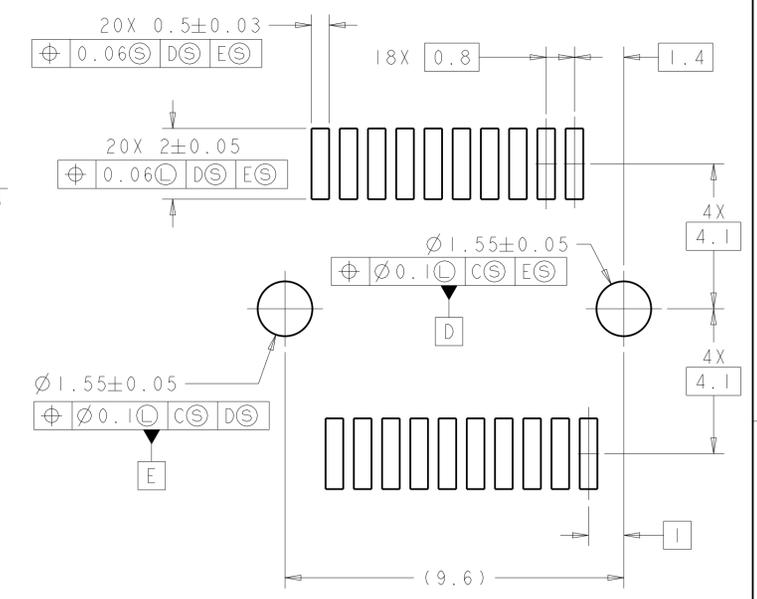
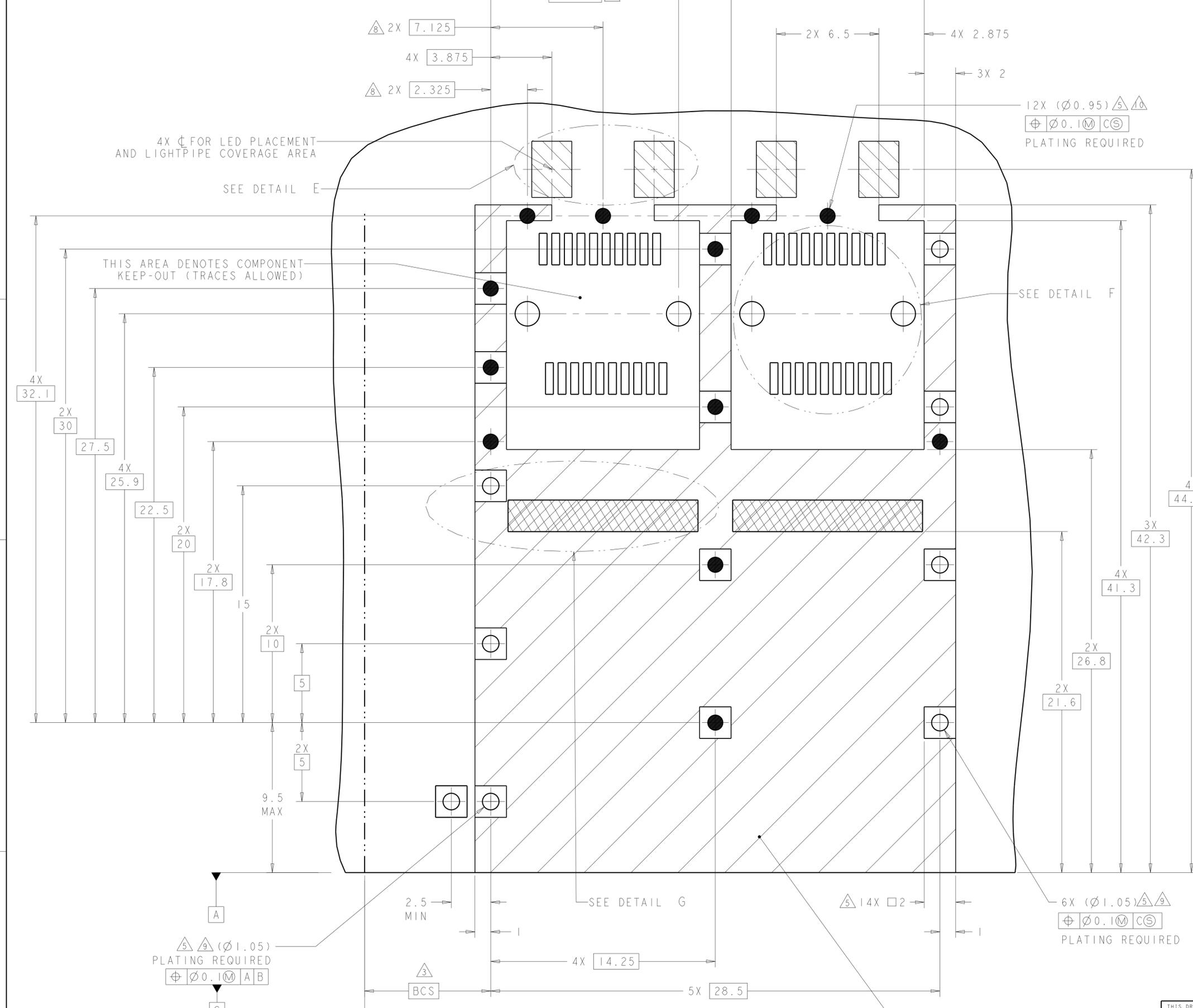
2198231
MOUNTED ON PC BOARD
SHOWN THRU RECOMMENDED BEZEL



2198231
MOUNTED BELLY TO BELLY ON PC BOARD
SHOWN THRU RECOMMENDED BEZEL

THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN: B. MATTHEWS 15NOV2011	TE Connectivity
DIMENSIONS: mm		CHK: M. SCHMITT 15NOV2011	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD: M. SCHMITT 15NOV2011	NAME: SFP+ ENHANCED 1X2 CAGE ASSEMBLY, PRESS-FIT, EXTERNAL EMI SPRINGS WITH HEATSINK AND LIGHTPIPE PRODUCT SPEC: 108-2364 APPLICATION SPEC: 114-13120
0 PLC ±0.13 1 PLC ±0.1 2 PLC ±0.08 3 PLC ±0.05 4 PLC ±0.05 ANGLES ±0.5		SIZE: 114-13120 WEIGHT: - Customer Drawing	
MATERIAL: FINISH: -		RESTRICTED TO: -	SCALE: 5:1 SHEET 2 OF 4 REV: A1

LOC	DIST	REV	DATE	APPV
GP	00			

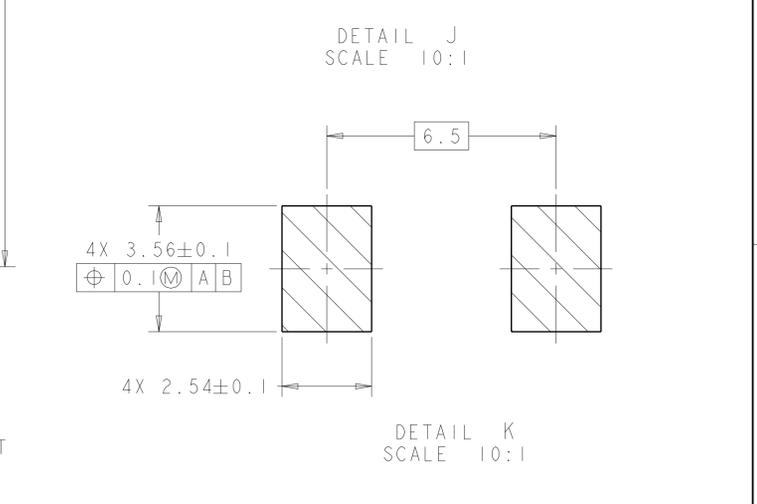
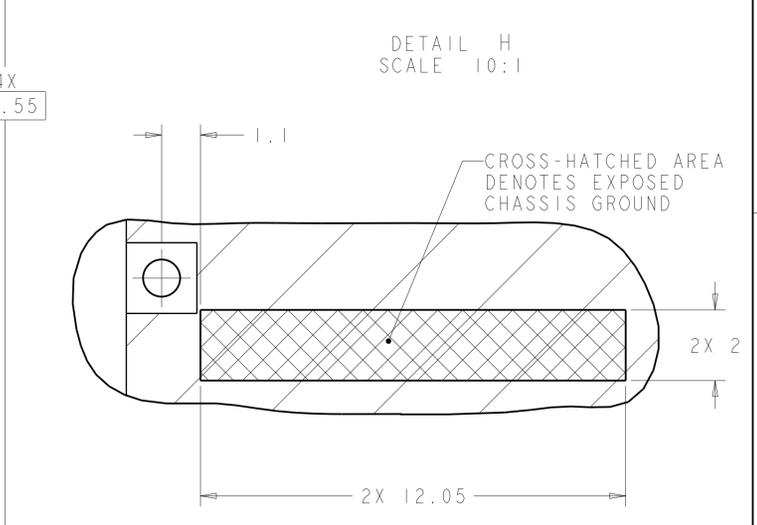
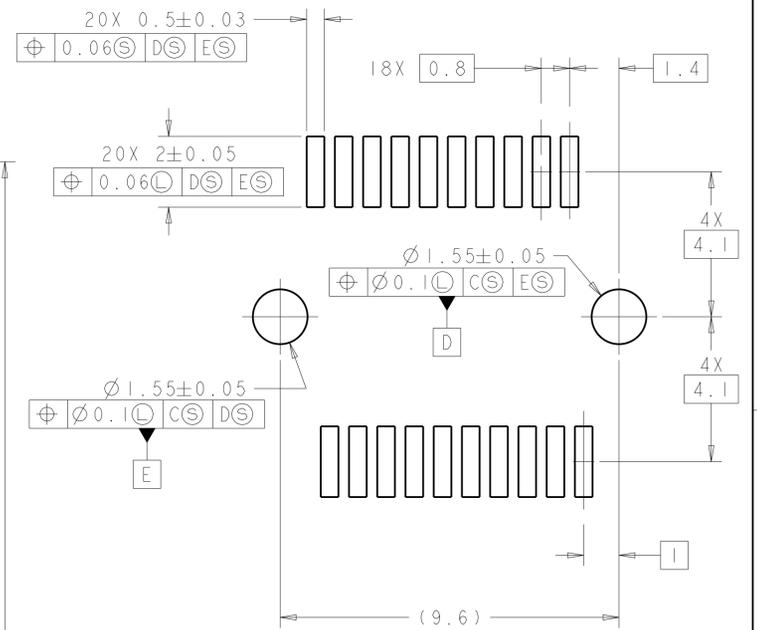
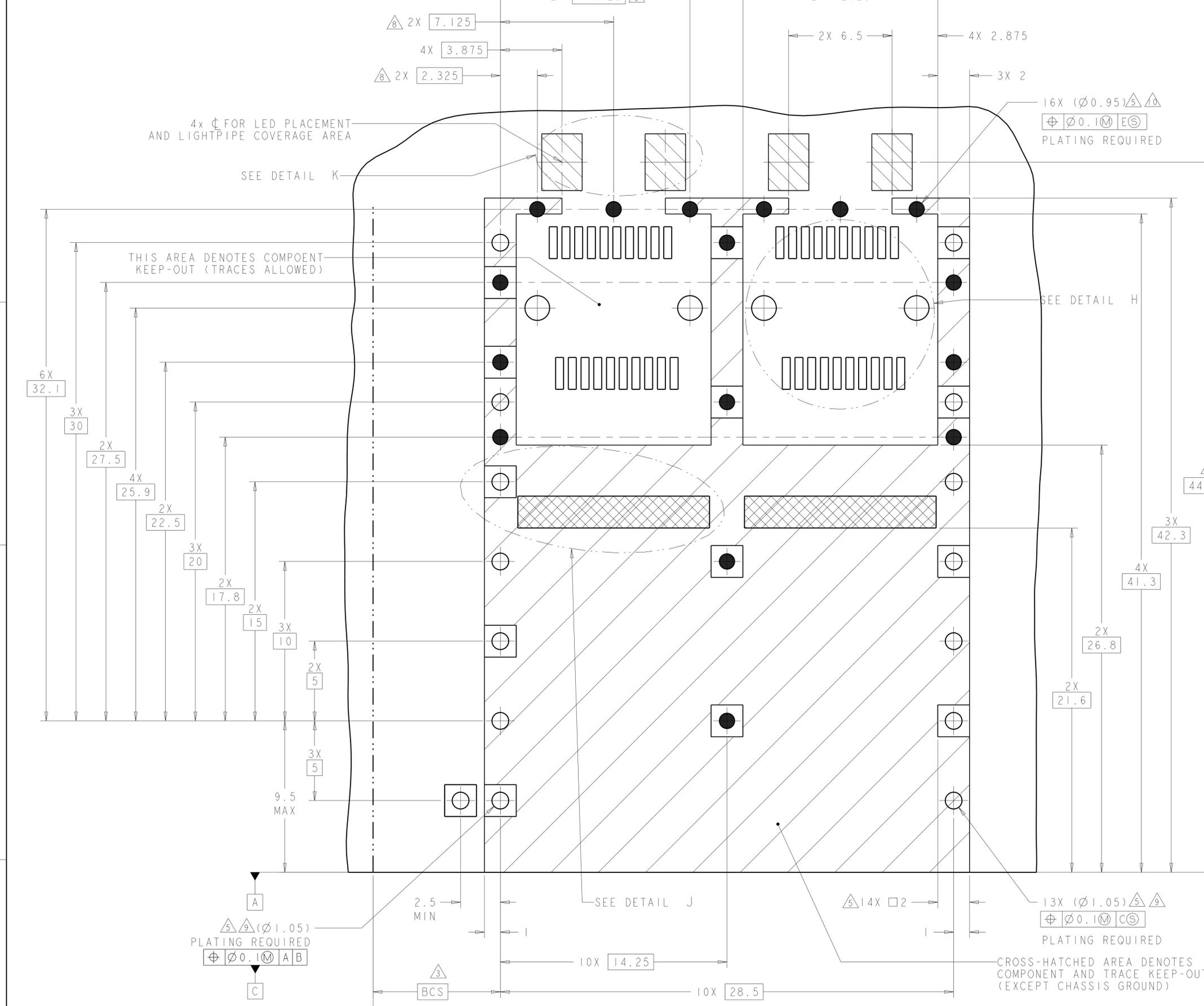


RECOMMENDED PCB CONFIGURATION WITH KEEP-OUT AREAS SINGLE SIDED APPLICATIONS SCALE 8:1

CROSS-HATCHED AREA DENOTES COMPONENT AND TRACE KEEP-OUT (EXCEPT CHASSIS GROUND)

THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN: B. MATTHEWS 15NOV2011	TE Connectivity
DIMENSIONS: mm		CHK: M. SCHMITT 15NOV2011	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD: M. SCHMITT 15NOV2011	NAME: SFP+ ENHANCED 1X2 CAGE ASSEMBLY, PRESS-FIT, EXTERNAL EMI SPRINGS WITH HEATSINK AND LIGHTPIPE
0 PLC ±0.13 1 PLC ±0.1 2 PLC ±0.08 3 PLC ±0.05 4 PLC ±0.05		PRODUCT SPEC: 108-2364	
MATERIAL: FINISH: ALL		APPLICATION SPEC: 114-13120	RESTRICTED TO: A100779C=2198231
		WEIGHT: -	SCALE: 5:1 SHEET 3 OF 4 REV: A1

LOC	DIST	REV	DATE	APPV
GP	00			



4x ϕ FOR LED PLACEMENT AND LIGHTPIPE COVERAGE AREA
 SEE DETAIL K
 THIS AREA DENOTES COMPONENT KEEP-OUT (TRACES ALLOWED)
 SEE DETAIL H
 CROSS-HATCHED AREA DENOTES EXPOSED CHASSIS GROUND
 CROSS-HATCHED AREA DENOTES COMPONENT AND TRACE KEEP-OUT (EXCEPT CHASSIS GROUND)
 PLATING REQUIRED
 PLATING REQUIRED
 PLATING REQUIRED
 PLATING REQUIRED
 RECOMMENDED PCB CONFIGURATION WITH KEEP-OUT AREAS BELLY TO BELLY APPLICATIONS SCALE 8:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN: B. MATTHEWS 15NOV2011	TE Connectivity
DIMENSIONS: mm		CHK: M. SCHMITT 15NOV2011	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APPV: M. SCHMITT 15NOV2011	NAME: SFP+ ENHANCED 1X2 CAGE ASSEMBLY, PRESS-FIT, EXTERNAL EMI SPRINGS WITH HEATSINK AND LIGHTPIPE PRODUCT SPEC: 108-2364 APPLICATION SPEC: 114-13120
0 PLC ±0.13 1 PLC ±0.1 2 PLC ±0.08 3 PLC ±0.05 4 PLC ±0.05		SIZE: 114-13120 WEIGHT: - Customer Drawing	
MATERIAL: FINISH: ALL		SCALE: 5:1	RESTRICTED TO: REV: A1

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

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Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

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